PATENT ABSTRACTS OF JAPAN

(11)Publication number:

2004-101642

(43)Date of publication of application: 02.04.2004

(51)Int.CI.

GO3F 7/039 HO1L 21/027

(21)Application number: 2002-260191

(71)Applicant: FUJI PHOTO FILM CO LTD

(22)Date of filing:

05.09.2002

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(54) RESIST COMPOSITION

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a resist composition which is suitably used in a supermicrolithography process and other photofabrication processes such as manufacture of VLSIs and high capacity microchips and whose surface roughness in etching is reduced, and further a resist composition which has superior characteristics of sensitivity, resolving power, a profile, a pattern fall, a side lobe margin, roughness and fineness dependency, etc.

SOLUTION: The resist composition contains (A) a resin which has a partial structure having a hydroxyl group replaced with a hydrocarbon group, has 120 to 180° C glass transition temperature, is decomposed by an acid and has its dissolution rate in an alkaline developing solution increased, (B) a compound which generates an acid by irradiation with an active ray or radiation, and (C) a solvent.

LEGAL STATUS

[Date of request for examination]

19.04.2005

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

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